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Product Change Notification - JAON-20EZAP999

Date: 21 Apr 2016
Product Category: Micrel
Notification subject: CCB 1737.02 Final Notice: Release to production of listed Micrel Power Switch product type manufactured with the BCD2 process technology to Microchip Fab.
Notification text: **PCN Status:**
 Final Notification

Note: This final PCN only pertains to the products listed in this PCN. Additional final PCNs may be issued for this combination of product type and process technology.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CP.N.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Release to production of listed Micrel Power Switch product type manufactured with the BCD2 process technology to Microchip Fab.

NOTE: Please review the FAQ linked [here](#) for additional information about this change.

Pre Change:

Fabricated at Micrel fabrication site (San Jose, CA, USA) using 6 inch wafers.

Post Change:

Fabricated at Microchip fabrication site using 8 inch wafers.

Pre and Post Change Summary:

	Pre Change	Post Change
Fab Site	Micrel fabrication site (San Jose, CA, USA)	Microchip fabrication site
Wafer Size	6 inch wafers	8 inch wafers

Impacts to Data Sheet:

None

Reason for Change:

To improve productivity with the closure of the Micrel fab as part of the integration of Micrel and Microchip.

Change Implementation Status:

In Progress

Estimated First Ship Date:

As identified for each CPN listed in the attached parts list.

Summary Time Table of notable events to date:

	September 2015					---->	February 2016				March 2016					April 2016				May 2016				
WW	36	37	38	39	40		05	06	07	08	09	10	11	12	13	14	15	16	17	18	19	20	21	
Initial PCN Issue Date CYER-31JLEX869	X																							
Qual Report Available JAON-22ZKEM744									X															
Final PCN Issue Date JAON-20EZAP999																	X							
Estimated First Ship Date																	As listed in the attached parts list.							

Markings to Distinguish Revised from Unrevised Devices:
Traceability code and shipping label see [FAQ](#).

Revision History:
September 1, 2015: Issued initial notification as PCN number [CYER-31JLEX869](#)
February 25, 2016: Issued intermediate notification as PCN number [JAON-22ZKEM744](#). Attached the Qualification Report. Revised the estimated first ship date (EFSD) to inform that the EFSD will be provided in the final PCN.
April 12, 2016: Issued final notification as PCN number [JAON-20EZAP999](#) for listed Micrel's Power Switch products manufactured with the BCD2 Process Technology. Provided estimated first ship date (EFSD) for each CPN listed in the attached parts list.
April 21, 2016: Re-issued the final notification with a new PCN number to be available in the website.

The change described in this PCN does not alter Micrel's or Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-22ZKEM744_Qual_Report.pdf](#)
[PCN_JAON-20EZAP999_Affected_CPN.pdf](#)
[PCN_JAON-20EZAP999_Affected_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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JAON-20EZAP999 - CCB 1737.02 Final Notice: Release to production of listed Micrel Power Switch product type manufactured with the BCD2 process technology to Microchip Fab.

Affected Catalog Part Numbers (CPN)

PCN_JAON-20EZAP999	
CATALOG_PART_NBR	Estimated First Ship Date (EFSD)
MIC2026-1YM	April 22, 2016
MIC2026-1YM-TR	May 15, 2016
MIC2027-1YM	May 15, 2016
MIC2027-1YM-TR	May 15, 2016
MIC2027-1YWM	May 15, 2016
MIC2027-1YWM-TR	May 15, 2016



MICROCHIP

QUALIFICATION REPORT
RELIABILITY LABORATORY

PCN #: JAON-22ZKEM744

Date
February 8, 2016

**Qualification of Microchip 8 inch Fabrication site for Micrel products
manufactured with the BCD2 Process Technology.**

PART NUMBER	PACKAGE TYPE	ASSEMBLY LOCATION	WAFER SIZE	PROCESS NAME
MIC2026-1YM /238A0/1	SOIC-8L	STARS, THAILAND	8"	BCD2

DIE QUALIFICATION RESULTS

TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	168 HR Rej/ss	500 HR Rej/ss	1000 HR Rej/ss	COMMENTS
HTOL High Temperature Operating Life Test	JESD22, Method 108	1542	V216.195868.000MQA	0/77	0/77	0/77	
	TA= + 125°C	1543	V216.195868.100MQA	0/77	0/77	0/77	
	VCC = 5.5V	1545	V216.216184.100MQA	0/77	0/77	0/77	

ELECTROSTATIC DISCHARGE

TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	STRESS	RESULT Rej/ss	COMMENTS
ESD-HBM Human Body Model ATE Test @ Room +25C	R= 1500 Ohms C= 100 pF 1X +/- Voltage	1542	V216.195868.000MQA	+/-500V +/-1000V +/-1500V +/-2000V	0/3 0/3 0/3 0/3	
ESD-CDM Charged Device Model ATE Test @ Room +25C	JESD22-C101 1X +/- Voltage	1542	V216.195868.000MQA	+/-200V +/-400V +/-1000V +/-1500V	0/3 0/3 0/3 0/3	

TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	STRESS	RESULT Rej/ss	COMMENTS
LATCH-UP	JESD-78 TA = +25°C	1542	V216.195868.000MQA	I/O LU O/V LU	0/6 0/6	

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PACKAGE QUALIFICATION RESULTS MCRL SPEC #100-1010

TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	Rej/ss	COMMENTS
Level 1 Pre-conditioning Flow	JESD22-A113	1542	V216.195868.000MQA	0/321	
		1543	V216.195868.100MQA	0/143	
		1545	V216.216184.100MQA	0/145	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	96 HR Rej/ss	COMMENTS
PRESSURE POT With Level 1 Pre- conditioning Tpeak + 260°C 3X Reflow	JESD22-A102 Ta = +121°C/100%RH 15 PSIG	1542	V216.195868.000MQA	0/45	
		1543	V216.195868.100MQA	0/45	
		1545	V216.216184.100MQA	0/45	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	96 HR Rej/ss	COMMENTS
HAST With Level 1 Pre- conditioning Tpeak + 260°C 3X Reflow	JESD22-A110 (BIASED) Ta= +130°C/85%RH JESD22-A118 (UNBIASED)	1542	V216.195868.000MQA	0/45	
		1543	V216.195868.100MQA	0/45	
		1545	V216.216184.100MQA	0/45	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	500 CY Rej/ss	COMMENTS
TEMP CYCLE With Level 1 Pre- conditioning Tpeak + 260°C 3X Reflow	JESD22-A104 Ta = -65°C / +150°C	1542	V216.195868.000MQA	0/45	
		1543	V216.195868.100MQA	0/45	
		1545	V216.216184.100MQA	0/45	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	1000 HR Rej/ss	COMMENTS
HTSL High Temperature Storage Life With Level 1 Pre- conditioning	JESD22-A103 Ta = +150°C	1542	V216.195868.000MQA	0/76	
		1542	V216.195868.000MQA	0/76	
HTSL High Temperature Storage Life With Level 1 Pre- conditioning	JESD22-A103 Ta = +175°C	1542	V216.195868.000MQA	0/76	
FLAMMABILITY	UL-94V-0 Certified	All mold compounds used by Micrel meet this standard. See the UL website on-line list of material flammability certifications. Micrel requires a Certificate of Compliance from the assembly house and we verify the certifications on the web.			